

**ENGLISH TRANSLATION
OF ARTICLE 34 AMENDMENT**

AMENDMENT (Amendment under Section 11)

To Mr. Tatsuya Ando, Examiner of the Patent Office

1. Indication of International Application

PCT/JP00/05553

2. Applicant

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4. Object of Amendment

Claims

5. Contents of Amendment

As shown in the attached sheets.

[Items to be amended]

(1) In claim 7 at pages 31 and 32, "A production method of a porous adhesive sheet, which comprises a step for forming a wire-containing film for forming an adhesive organic film having plural wires running in about parallel with each

other in the thickness direction thereof, and a wire-removing step for removing the wire in said organic film, wherein the wire is covered with an organic material layer having a softening temperature higher by 10°C or more than the softening temperature of the organic film" is amended to read "A production method of a porous adhesive sheet having plural through holes running in about parallel with each other in the thickness direction of an adhesive organic film, which are surrounded by an organic material layer having a softening temperature higher by 10°C or more than the softening temperature of the organic film, which method comprises a step for forming a wire-containing film, comprising covering the wire with an organic material having a softening temperature higher by 10°C or more than the softening temperature of the adhesive organic film and forming a wire-containing film, such that plural wires run in about parallel with each other in the thickness direction of the adhesive organic film, and a wire-removing step for removing the wire in the organic film".

6. List of the Annexed Documents

- (1) Claims on pages 31 and 32 One copy